

| | Type | L # | Hits | Search Text | DBs | Time Stamp | Cor ro mm en ts | De ni ti on | Er ro rs |
|---|------|-----|------|---|---|---------------------|-----------------------------|----------------------|----------------|
| 1 | BRS | L7 | 56 | (438/458) .ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2006/03/03 18:32 | | | |
| 2 | BRS | L9 | 81 | (438/459) .ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2006/03/03 18:34 | | | |
| 3 | BRS | L15 | 78 | ("438"/\$) .ccls. and (bond\$4 or join\$4) near oxide with (carrier or support\$4 or handle) near (wafer or substrate or die) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2006/03/03 18:36 | | | |

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| 4 | BRS | L3 | 4 | (438/464) .ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and align\$5 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2006/03/03 18:43 | | | |
| 5 | BRS | L16 | 16 | ("20030205796" "20030218236" "4962879" "5324687" "5532519" "5567653" "5712190" "6010591" "6025638" "6110806" "6279815" "6333553" "6365966" "6541871" "6633086" "6926937") .PN. OR ("7005319") .URPN. | US-PGPUB; USPAT; USOCR | 2006/03/03 18:47 | | | |

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| 6 | BRS | L4 | 9 | (bond\$4 or join\$4) near oxide near (carrier or support\$4 or handle) near (wafer or substrate) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and align\$5 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2006/03/03 18:51 | | | |
| 7 | BRS | L5 | 23 | (bond\$4 or join\$4) near oxide near (carrier or support\$4 or handle) near (wafer or substrate) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2006/03/03 18:52 | | | |
| 8 | BRS | L6 | 7 | (438/464).ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2006/03/03 19:26 | | | |

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| 9 | BRS | L8 | 14 | (438/456) .ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2006/03/03 19:02 | | | |
| 10 | BRS | L17 | 46 | ("5006487" "5216490" "5310450" "5326726" "5329110") .PN. OR ("5668033") .URPN. | US-PGPUB; USPAT; USOCR | 2006/03/03 19:07 | | | |
| 11 | BRS | L10 | 2 | (438/421) .ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2006/03/03 19:14 | | | |

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| 12 | BRS | L13 | 21 | ((bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) near (wafer or substrate or die) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)).clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2006/03/03 19:15 | | | |
| 13 | BRS | L11 | 28 | (438/977).ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2006/03/03 19:18 | | | |
| 14 | BRS | L21 | 17 | (bond\$4 or join\$4) near oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or singulat\$4) with separat\$4 and plan\$7 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2006/03/03 19:29 | | | |

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| 15 | BRS | L22 | 80 | (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or singulat\$4) with separat\$4 and plan\$7 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2006/03/03 19:30 | | | |
| 16 | BRS | L23 | 2 | ((bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or singulat\$4) with separat\$4 and plan\$7).clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2006/03/03 19:30 | | | |
| 17 | BRS | L24 | 42 | ("438"/\$).ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or singulat\$4) with separat\$4 and plan\$7 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2006/03/03 19:34 | | | |

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| 18 | BRS | L25 | 40 | ("257"/E21.\$).ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or singulat\$4) with separat\$4 and plan\$7 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2006/03/03 21:07 | | | |
| 19 | BRS | L26 | 0 | ("257"/E21.606).ccls. and (bond\$4 or join\$4) with oxide with (carrier or support\$4 or handle) with (wafer or substrate) and (dic\$4 or cut\$5 or singulat\$4) with separat\$4 and plan\$7 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | 2006/03/03 21:08 | | | |